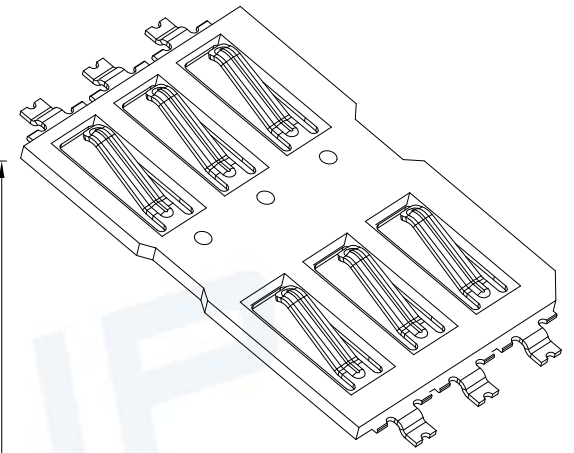
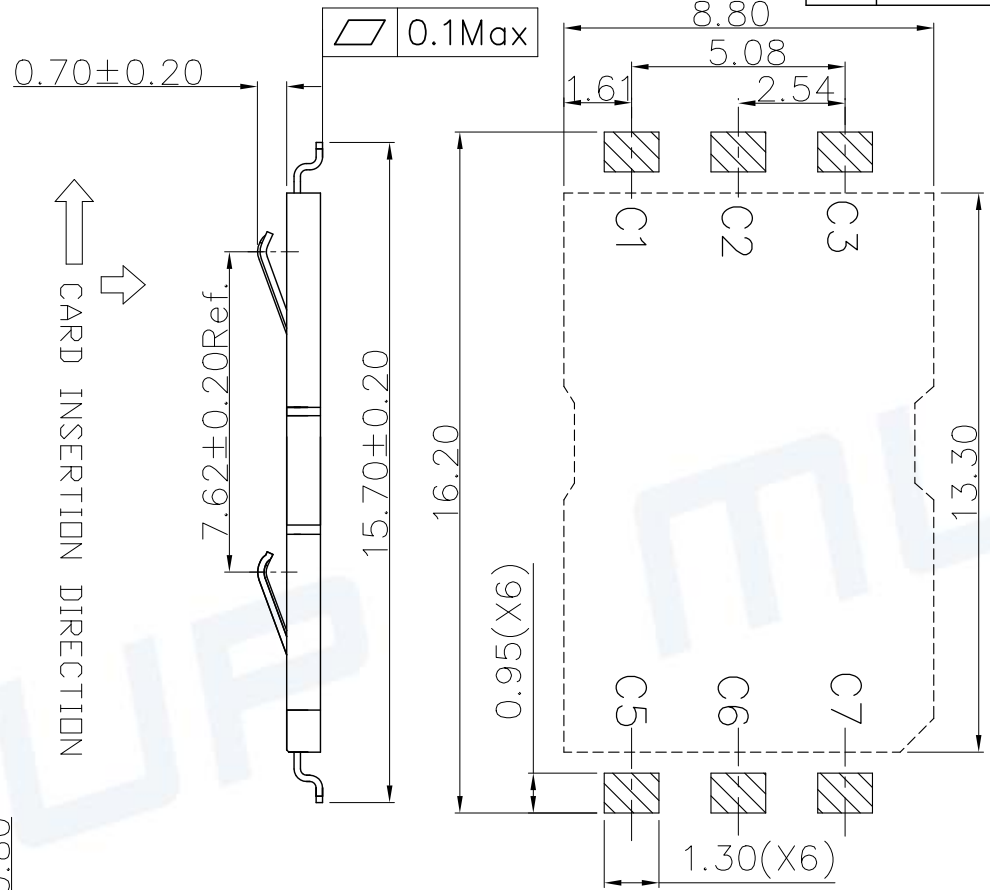
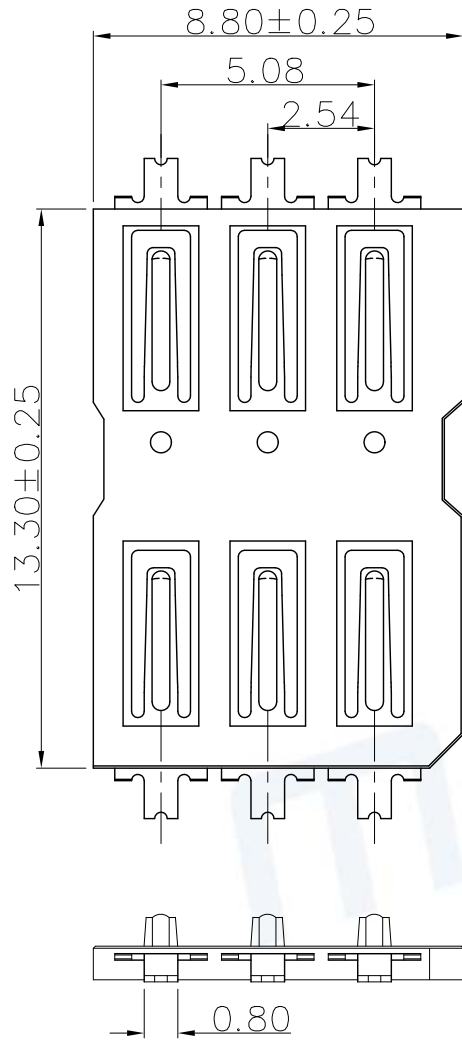


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1	NEW REVISION				Sep.13.2010
X2					



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

TECHNICAL CHARACTERISTICS
 1.General Characteristics
 Dimensions:13.30LX8.80WX0.50H mm
 Weight:Approx 0.13±0.1g
 Durability:5,000 cycles min.
 2.Electrical Characteristics
 Contact resistance:50mΩ typical,100mΩ max
 Insulation resistance:>1000MΩ/500V DC
 3.Solderability
 Vapor phase:215°C,30sec.Max
 IR reflow:250°C,5sec.Max
 Manual soldering:370°C,3sec.Max
 4.Environmental Characteristics
 Operating temperature:-40°C~+85°C
 Operating humidity:10%~+95%RH

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated

Unless otherwise specified, other tolerance are:

X	±0.35	X*	±5*
X.X	±0.25	X.X*	±4*
X.XX	±0.15	X.XX*	±3*
X.XXX	±0.10	X.XXX*	±2*

MUP MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**
 MODEL NO: **MUP-C726-21**
 TYPE: **6pin H0.80 mm**

PROJ.	UNIT	SCALE	DRAWN	Zoey Sep.13.2010	DWG NO.:
	mm	1:1	CHECKED	Jimmy Sep.13.2010	DWG-MUP-C726-21
CUSTOMER DRAWING			APPROVAL	Simon Sep.13.2010	SHEET
					1/1
					REVISION
					X1

